

Thick and Thin Film Chip Component Trim System



LT3210 & LT4210

ChipR Trim™

High performance Chip Trim System designed specifically
for Thick and Thin Film Components down to the latest 01005 products.

ChipR Trim™ LT3210 & LT4210

Specifications

Optical System

• Beam positioner type	High Speed closed loop galvanometer
• Spot Size ¹	15 µm 10 µm (optional)
• Field size	75 x 10 mm 50 x 10 mm (10 µm spot)
• Depth of Focus	150 µm 50 µm (10 µm spot)
• Positioning Accuracy	± 25 µm ± 12 µm (10 µm spot)
• Repeatability	± 6.25 µm ± 5.00 µm (10 µm spot)
• Resolution	1.54 µm 0.76 µm (10 µm spot)

¹ Minimum spot size. Maximum = 1.5X minimum.

Laser System

• Type	Diode pumped Q-switched YAG
• Wavelength	532 nm
• Output Power / Pulse Width	3W / 30 ns 3W / 70ns (optional)

X/Y/Z Part Positioning

• Closed loop servo controlled stepper	
X/Y Travel	100 mm x 200 mm
X/Y Resolution	1 µm
• Probing	
Z force	10 lbs (4.5 kg)
• Part Stage	
• Choice of edge or center snugging	
• Venturi generated vacuum hold down	
• ± 3.0° stage rotation with 0.001° resolution	

Part Viewing

• Dual CCD camera system for High and Low Mag viewing	
• 15 µm (nominal factory settings)	
High Mag Viewing Field	1.7 x 1.2 mm
Low Mag Viewing Field	11.0 x 8.0 mm
• 10 µm (nominal factory settings)	
High Mag Viewing Field	1.1 x 0.83 mm
Low Mag Viewing Field	6.0 x 4.5 mm
• Vision Processing Choices	
Pattern recognition with Edge Detection or Edge Detection.	

Measurement System

• Type	High Speed, Force V, current nulling bridge	
• Range	0.1Ω – 1000 MΩ	
• Resistance measurement accuracy (full Kelvin)		
Low Range (< 50Ω)	± 0.02% ± (1.0%/R)	
Mid Range	± 0.02% of value	
High Range (> 160 K)	± 0.02% ± 0.02% per MΩ	
• Active Guard Measurement		
200 mA guard driver		
• DC Voltage Measurement Accuracy		
Range	Accuracy (%FSR)	
100 mV – 400 mV	± 0.10%, ± 1 mV	
1V – 16V	± 0.05%, ± 1 mV	
10V – 160V	± 0.05%, ± 5 mV	
• Voltage Source		
Range	Resolution	Accuracy (%FSR)
± 4V	31 µV	± 0.008 %
± 16V	125 µV	± 0.005 %
± 32V	250 µV	± 0.005 %

Handler Subsystem

• Substrates	50 mm x 60 mm 60 mm x 70 mm (optional)
• Stacks	2 input, 1 output (Capacity dependent on substrate thickness)
• Stack Height	75, 145, 275 mm (selectable)
• Pick & Place	Adjustable mini-suction cups
• Snugger	Edge Snugger Center snugger (optional)

Software

• ChipTrim	standard software Multi-lot, multi-job processing
• VersiTrim	Laser trim language library Microsoft® C/C++ Compiler
• Windows™ 10 Operating System	

Utility Requirements

• Power	100 / 120 / 230 / 240 VAC ± 10%
• Air	50 / 60 Hz, single phase 20 A max 80 psi @ 4 SCFM (113 l/m) filtered to 5 µm and free of contaminants

Optional Equipment

• Low-ohm option (5 mΩ – 1 Ω)	
• Uses standard 4T probe cards	
• Range	Accuracy
0.005 Ω – 0.1 Ω	± 0.50 %
0.1 Ω – 1 Ω	± 0.25 %
• Additional matrix	
• GPIB interface	
• GPIB instrumentation package	

Benefits

- Spot size down to 10 microns
- Patented 532 nm diode-pumped laser technology for minimum maintenance, long term stability and high reliability
- Patented beam calibration and vision system for automatic alignment and precise laser positioning
- High Speed handler manages thin substrates used with the latest generation small geometry chip resistors

- Wide range measurement system
 - 5 milli-Ohms to 1 Gig Ohm
 - Traceable measurement certification
- ChipTrim™ Software
 - Graphical user environment dedicated to chip trimming
 - Globalized language support